



# Test Development, Test Strategy and Good Practice

March 2019

Moscow

## Key ASIC Test Services

- In-house HW & SW development
  - Wafer level (CP) & package level (FT)
- Wide experiences in ASIC test
  - RF, mixed signal, analog and digital
- Production management and optimization
  - Yield, quality and cost
- Various tester choices for different performance/cost requirements

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|      | TEST         |
|      | PKG          |

## Test Partners

**Chroma**



Orient Semiconductor Electronics

**Vate**

立衛科技股份有限公司  
Vate Technology Co.,Ltd.

**Testar**  
LED/SEMICONDUCTOR TEST SERVICES



Global Testing Corporation  
寰邦科技股份有限公司



True Test Technology Inc.

**ADVANTEST®**

**TERADYNE**

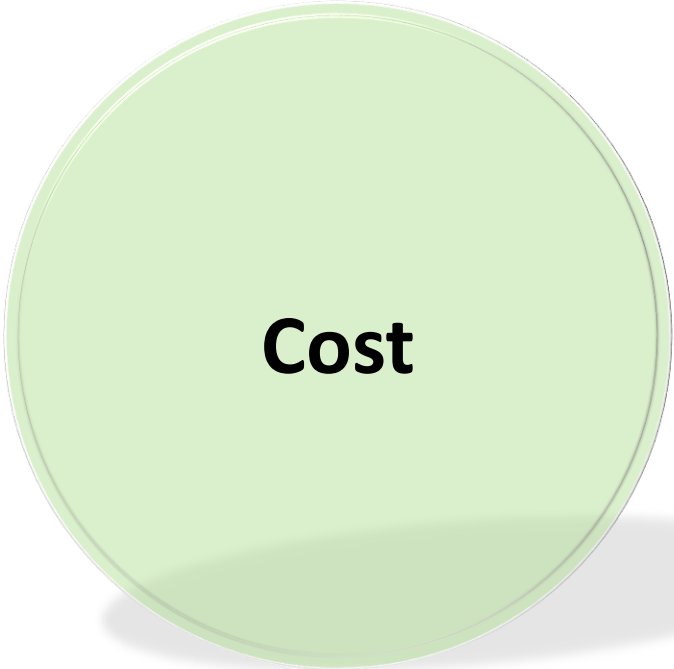
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## ASIC Test Objectives



**Reliable**

**Maximize Test Coverage**



**Cost**

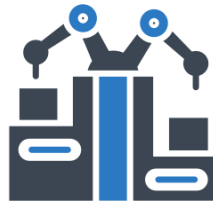
**Minimize Test Time**

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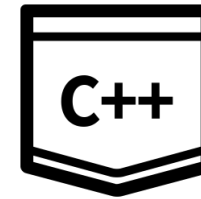
# ASIC Test Strategy



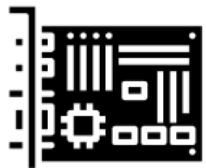
**Test Requirement**



**Tester Selection**



**Test Program Development**



**Hardware Development**



**Silicon Debug**



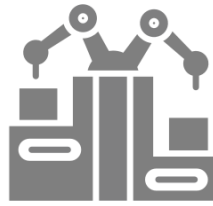
**Optimization**

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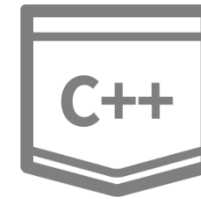
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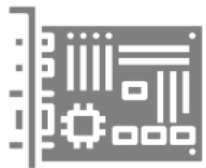
**Test Requirement**



**Tester Selection**



**Test Program Development**



**Hardware Development**



**Silicon Debug**



**Optimization**

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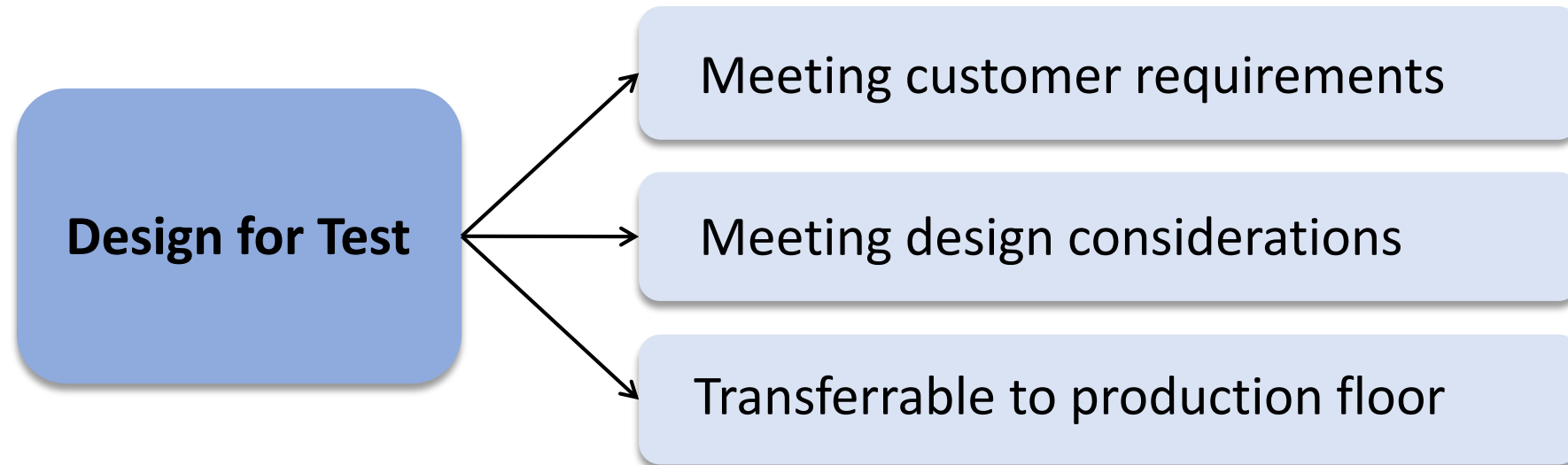
## Test Requirement

- Cross-functional involvement
  - Customer, design engineer, DFT engineer, test engineer
- Define the level of test coverage required
  - DFT implementation, functional tests
  - Example:
    - To implement  $I_{DDQ}$  test, design could incorporate a global signal line that shuts down the current drawing circuitry.
- Number of IO pins, test frequency, temperature
- Finalize test plan

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## Design for Test

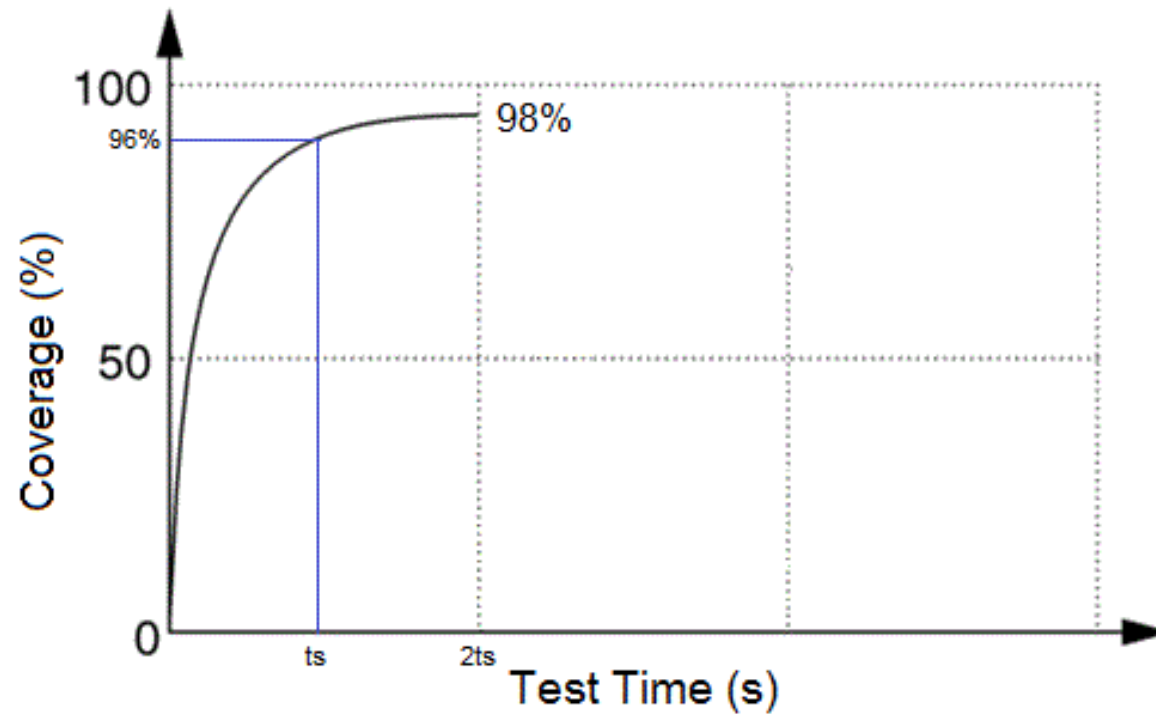
- ATPG scan, Boundary-scan cells and Memory BIST



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## Stuck-at Coverage vs Test Time



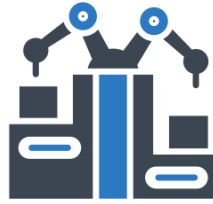
Trade-off between coverage and test time

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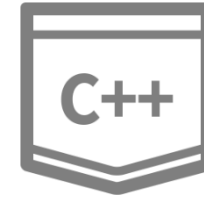
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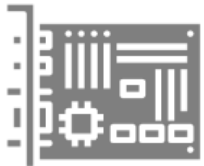
Test Requirement



**Tester Selection**



Test Program  
Development



Hardware  
Development



Silicon Debug



Optimization

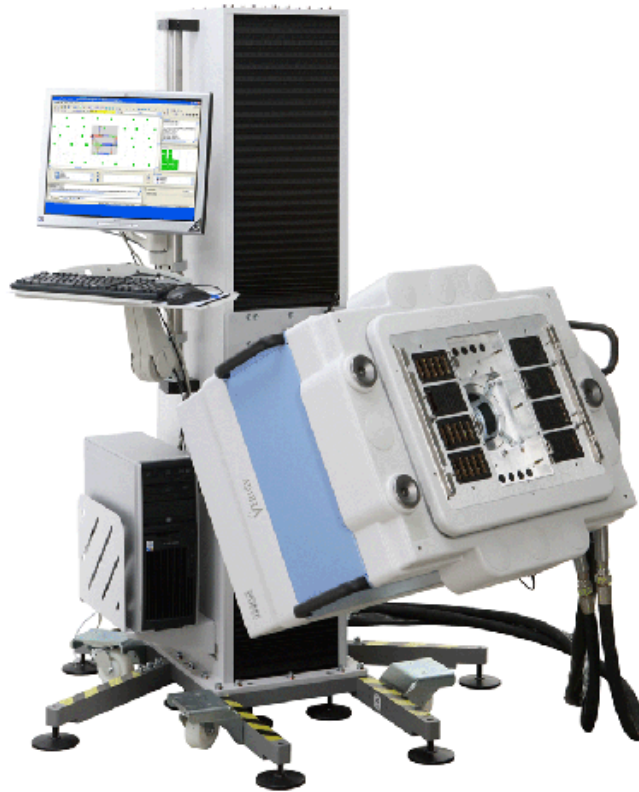
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## Tester Selection

IC Function  
Eg: (AD/DA)

Package  
Type

Pin Count



Test  
Frequency

Vector  
Memory

Cost

Availability

|      |              |
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## Tester Selection

Lower Cost

High Cost



VLSI Test System  
Model 3360-P

- 50 Mhz clock rate, 256 I/O channels
- Up to 32 sites Parallel testing
- Support ADDA, Mixed-signal , LCD ...etc option card
- Flexible Architectures: Slot interchangeable I/O, ADDA, UVI, HVREF ...etc option



VLSI Test System  
Model 3380-P

- 100Mhz clock rate, 512 I/O channels (Max to 576 pins)
- Up to 512 sites Parallel testing
- Various VI source
- Flexible Architectures: Slot interchangeable I/O, ADDA, VI source



Advanced SoC/Analog Test System  
Model 3680

- Application coverage:MCU, Digital Audio, DTV, STB, DSP, Network Processor and Field, FPGA
- 24 interchangeable slots for digital,analog and mixed-signal applications
- 150 Mbps up to 1Gbps data rate (muxed)

Lower Range

Advanced

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## Tester Selection - Other Factor

- In reality, the testing cost of the tester varies from one test vendor to another
  - Production Capacity
  - Utilization
- The cost by vendor A can be 20-30% cheaper than vendor B
- The benefit of having multiple test vendors in order to maintain cost competitive

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## Tester Model

| Tester           | Clock Rate | Tester             | Clock Rate    |
|------------------|------------|--------------------|---------------|
| Credence ASL1000 | 14 MHz     | Teradyne J750EX    | 200 ~ 400MHz  |
| Chroma 3360P2    | 50 MHz     | Teradyne J750EX-HD | 400 ~ 800 MHz |
| Credence SC312   | 50 MHz     | Teradyne CATALYST  | 400 MHz       |
| Chroma 3380      | 100 MHz    | Chroma 3680        | 500 MHz       |
| Chroma 3650      | 100 MHz    | Teradyne Tiger     | < 1 GHz       |
| Teradyne J750    | 200 MHz    | Xcerra Diamondx    | < 1 GHz       |
| Chroma 3650EX    | 200 MHz    | Advantest V93000   | < 1 GHz       |
| KYEC E320        | 200 MHz    | Teradyne UltraFLEX | < 2 GHz       |
| Teradyne Flex    | 200 MHz    |                    |               |

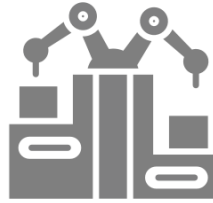
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Tester model which available at our test vendor's site

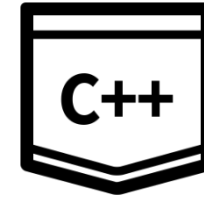
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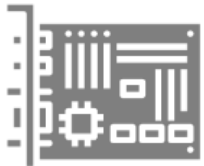
Test Requirement



Tester Selection



**Test Program  
Development**



Hardware  
Development



Silicon Debug



Optimization

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## Test Program Development

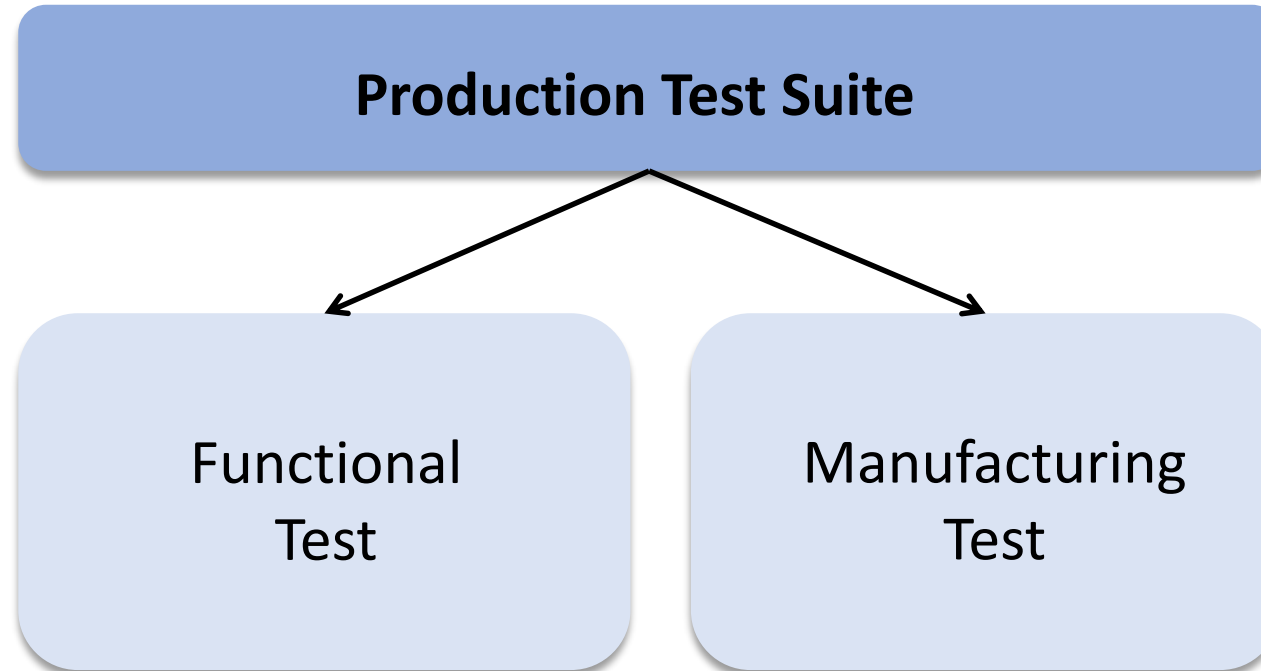
- **Patterns simulation (DFT Engineer/Customer)**
  - DFT pattern, functional pattern
- **In-house CP/FT program development**
  - **Test coding, pattern conversion & simulation**
    - ATPG Scan : TSTL2/STIL -> .pat
    - MEMBIST: EVCD -> .pat
    - Boundary scan: EVCD -> .pat
- **Pre-production program validation**

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# Test Types

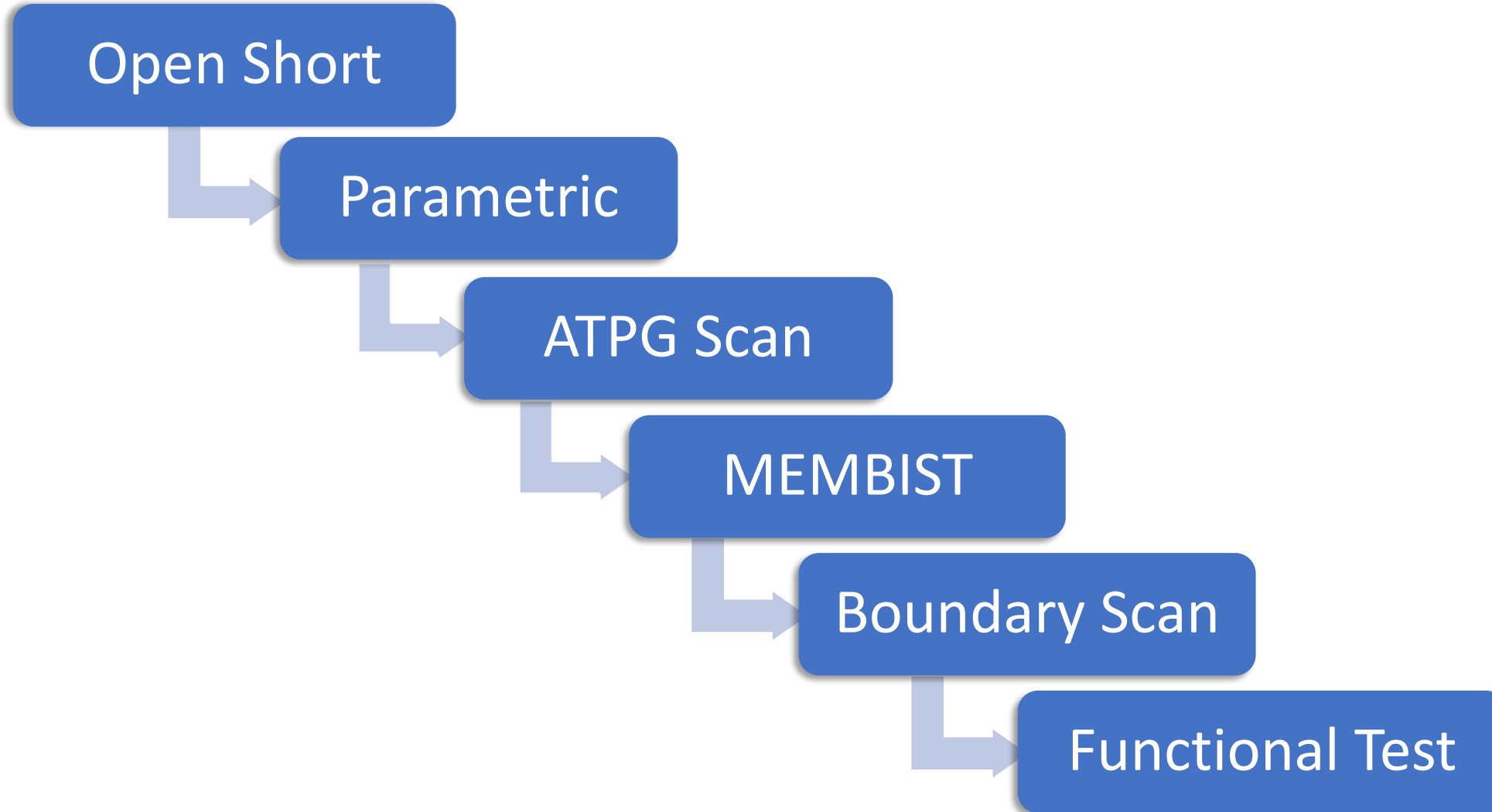
- Ensure performance meeting design spec
- Long test time
- Eg: Functionality of IP block
- Is it necessary?



- Detect ASIC manufacturing defect
- Short test time
- Eg: Open short, leakage current, scan test, MEMBIST test, boundary scan

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## Test Program Flow

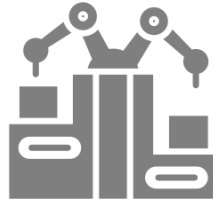


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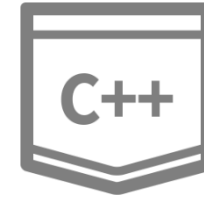
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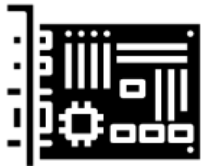
Test Requirement



Tester Selection



Test Program Development



Hardware Development



Silicon Debug

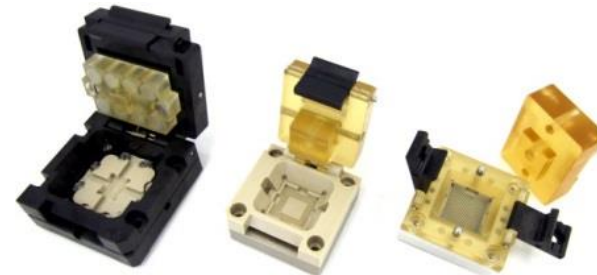


Optimization

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## Test Hardware

- Test board design & requirement
  - Power assignment, temperature, speed, relay requirement
  - Challenges -> trace length, noise, cross-talk
- Socket
  - Package type, temperature, life cycle
- Hardware fabrication lead time
  - 2 – 4 months
- Offline hardware check

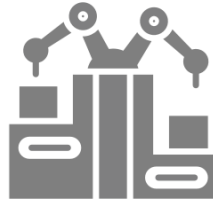


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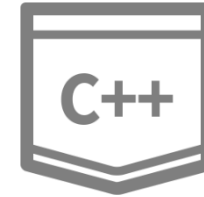
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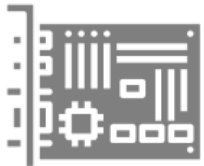
Test Requirement



Tester Selection



Test Program  
Development



Hardware  
Development



Silicon Debug



Optimization

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## Silicon Debug

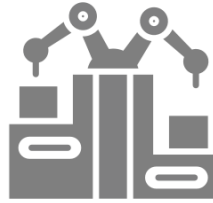
- To ensure the design is working as expected
- Cross functional effort between design engineer, DFT engineer and test engineer
- Steps to a complete silicon debug
  - Start with open short and parametric tests to make sure there is no electrical defect
  - Follow by ATPG Scan test which has the largest fault coverage
  - Bring up the remaining DFT test – MEMBIST and Boundary scan
  - Complete with functional tests

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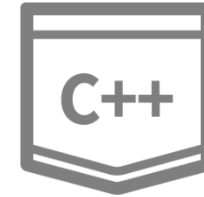
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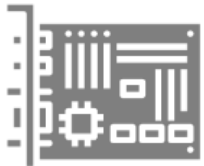
Test Requirement



Tester Selection



Test Program  
Development



Hardware  
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Silicon Debug



**Optimization**

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## Test Time Optimization

- Improve test program coding
- Reduce wait/delay time
- Reduce relay switching
- Do not power off after pattern completed
- Parallel/group voltage/current measurement
- Increase test frequency
- Pattern removal (low coverage / low DPM)

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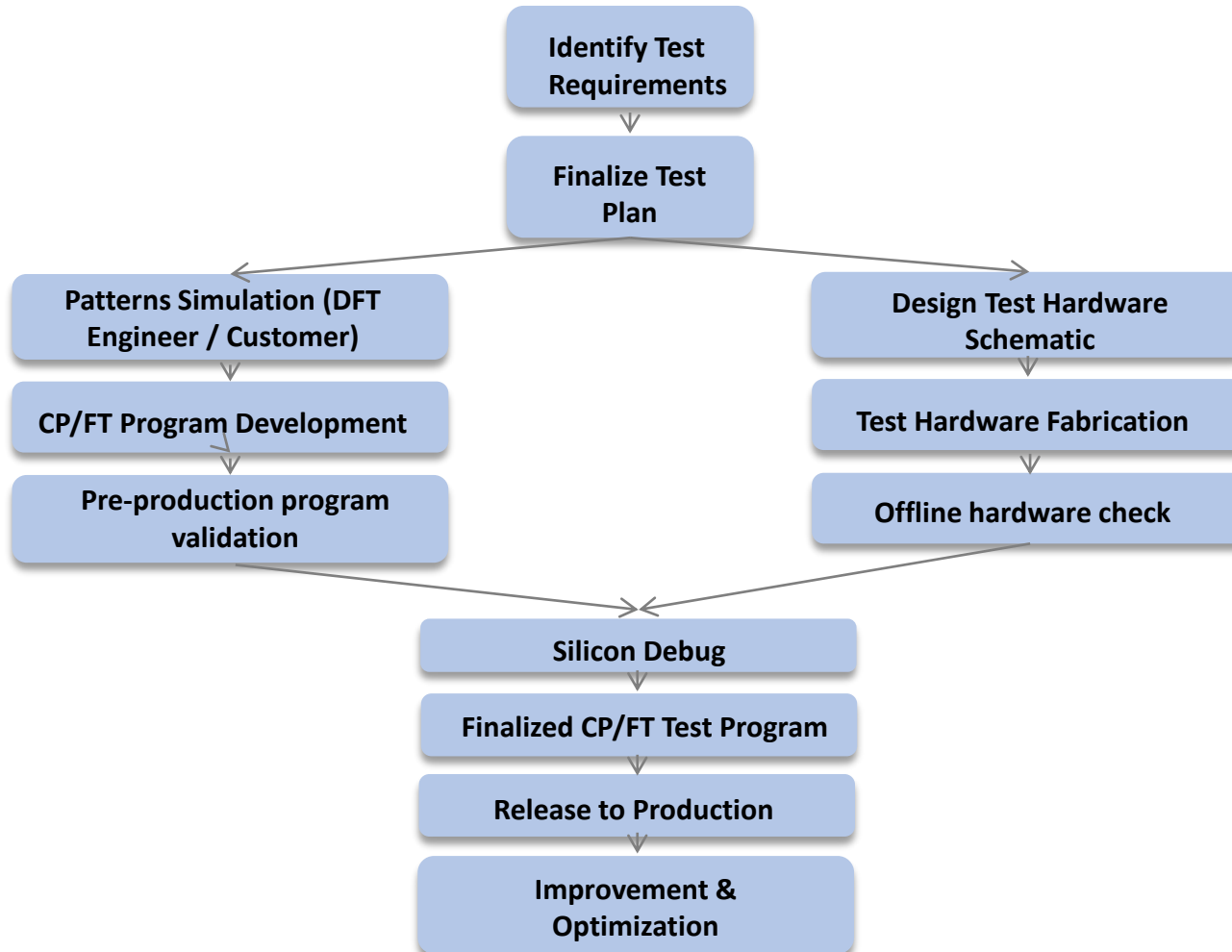


## Summary

- A good and effective ASIC testing require early involvement of test engineer
- Cross functional effort is important
  - Customer, design engineer, DFT engineer, test engineer
  - From identifying test requirement to silicon debug
- Each and every strategy in the flow need to be executed correctly
- Production optimization
  - Continuous test cost important

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# Effective ASIC Testing Flow



**keyASIC**

Thank You